

## C1206C472K2TACTU

Aliases (C1206C472K2TAC7800) SMD Comm X8G HT150C, Ceramic, 4,700 pF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

		Specifications
	1206	Capacitance
	3.2mm +/-0.2mm	Measurement Condition
	1.6mm +/-0.2mm	Tolerance
	0.78mm +/-0.10mm	Voltage DC
	1.5mm MIN	Dielectric Withstanding Voltag
	0.5mm +/-0.25mm	Temperature Range
		Temp. Coefficient
ecifications		Capacitance Change with
	T&P 180mm Plastic Tape	Reference to +25°Č and 0 VD0

Packaging Specifications	
Packaging	

Dimensions Chip Size

L W T S B

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Specifications	
Capacitance	4,700 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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